

Title (en)

SENSOR MICRO-MACHINED WITH ELECTROLYTIC WELDING AND METHOD FOR MAKING SAME

Title (de)

MIKROVERARBEITETER SENSOR MIT ELEKTROLYTISCHER SCHWEISSUNG UND DESSEN HERSTELLUNGSVERFAHREN

Title (fr)

CAPTEUR MICRO-USINE AVEC SOUDURE ELECTROLYTIQUE ET PROCEDE DE FABRICATION

Publication

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Application

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Abstract (en)

[origin: WO0215257A1] The invention concerns sensors of physical quantities such as pressure or acceleration sensors, or more precisely the mounting of the active part of the sensor on a base plate (30) bearing connection pins (32). The invention is characterised in that it consists in: preparing an active part of the sensor, consisting for example of micro-machined silicon plates (10, 12) bearing electronic components, electrical conductors, and bond pads (22); likewise preparing a base plate (30) provided with pins (32) whereof the top ends are arranged in the space each opposite a respective pad (22); pressing the surface bearing the pads against the top part of the pins, and immersing the whole assembly into an electrolytic solution to deposit metal (34) which is urged to rigidly weld the pins on the pads. Preferably the conductive parts (pads and pins) of the assembly are then covered with an insulation (36), to avoid electrical leaks between the pins subjected to different potentials.

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IPC 8 full level

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